(CMP)陶瓷载盘

(CMP) Ceramic Block

Ceramic block is made of high purity and ultra-fine alumina powder by high temperature curing.

陶瓷载盘采用高纯超细氧化铝粉体经高温烧制而成.

Main features: High purity, less impurities, high hardness,wear resistance and corrosion resistance. High precision, small thermal expansion coefficient and good accuracy retention, good wear resistance and corrosion resistance.

主要特点：具有纯度高、杂质少、硬度高、耐磨耐腐蚀等特点，并且产品精度高、热膨胀系数小、精度保持性好.

Application: It is mainly used for thinning, hard polishing and CMP polishing of LED substrate and semiconductor wafers(sapphire wafer, SiC wafer,silicon wafer, germanium wafer, GaAs wafer, GaN wafer, etc.).

用途：主要用于 LED 衬底及半导体晶圆（蓝宝石片、碳化硅片、硅片、锗片、砷化镓片、氮化镓片等）及其材料晶圆及窗口片的减薄、硬抛及 CMP 抛光制程。

Model specification and tolerance 规格及精度

外径范围 /mm Outer diameter	平面度 /mm Flatness	平行度 /mm Parallelism
≤ 200	0.001	0.0015
200 < D ≤ 305	0.001	0.003
305 < D ≤ 385	0.0015	0.004
385 < D ≤ 600	0.002	0.005